UNITED STATES PATENT AND TRADEMARK OFFICE **CERTIFICATE OF CORRECTION**

PATENT NO.

: 7,081,660 B2

Page 1 of 5

DATED

APPLICATION NO. : 09/884844 : July 25, 2006

INVENTOR(S)

: Robert L. Payer

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

The title page showing the illustrative figure should be deleted to be replaced with the attached title page.

Drawing sheets, consisting of figs. 1, 2, and 3, should be deleted to be replaced with the drawing sheets, consisting of figs. 1, 2, and 3, as shown on the attached page.

Signed and Sealed this

Fourth Day of March, 2008

JON W. DUDAS Director of the United States Patent and Trademark Office

(12) United States Patent Payer

(10) Patent No.: US 7,

US 7,081,660 B2

(45) Date of Patent:

Jul. 25, 2006

(54) HERMETIC PACKAGE WITH INTERNAL GROUND PADS

(75) Inventor: Robert L. Payer, Pepperell, MA (US)

(73) Assignee: Axsun Technologies, Inc., Billerica,

MA (US)

(*) Notice: Subject to any disclaimer, the term of this

patent is extended or adjusted under 35 U.S.C. 154(b) by 764 days.

0.5.C. 154(0) by 704

(21) Appl. No.: 09/884,844

(22) Filed: Jun. 19, 2001

(65) Prior Publication Date

US 2002/0190335 A1 Dec. 19, 2002

(51) Int. Cl. H01L 23/495 (2006.01) H01L 23/52 (2006.01) H01L 23/02 (2006.01)

See application file for complete search history.

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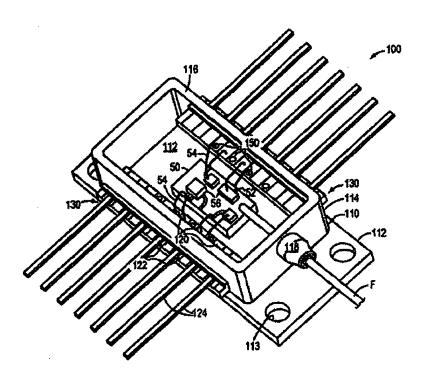
Primary Examiner—Nathan J. Plynn Assistant Examiner—Fazli Erdem

(74) Attorney, Agent, or Firm-Houston Eliseeva LLP

(57) ABSTRACT

An optoelectronic hermetic package comprises a frame defining a hermetic boundary and an electrical feedthrough assembly on the frame. This electrical feedthrough assembly provides electrical connections between signal wire bond areas within the hermetic boundary to electrical contact areas outside the hermetic boundary. Additionally, according to the invention, ground wire bond pad areas are also provided within the hermetic boundary, the ground wire bond pad areas being electrically connected to each other and/or the frame or other ground plane.

12 Claims, 3 Drawing Sheets



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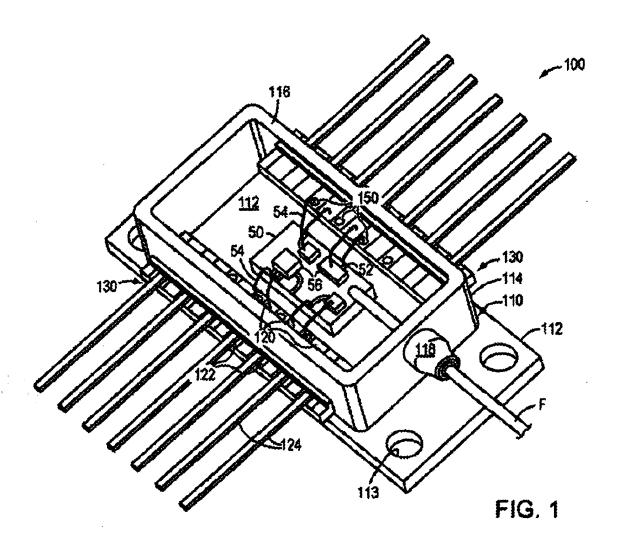
APPLICATION NO. : 09/884844

INVENTOR(S)

: July 25, 2006 : Robert L. Payer

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Delete Sheet 1 of 3 of the issued patent and replace with the following sheet 1 of 3:



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APPLICATION NO. : 09/884844

DATED

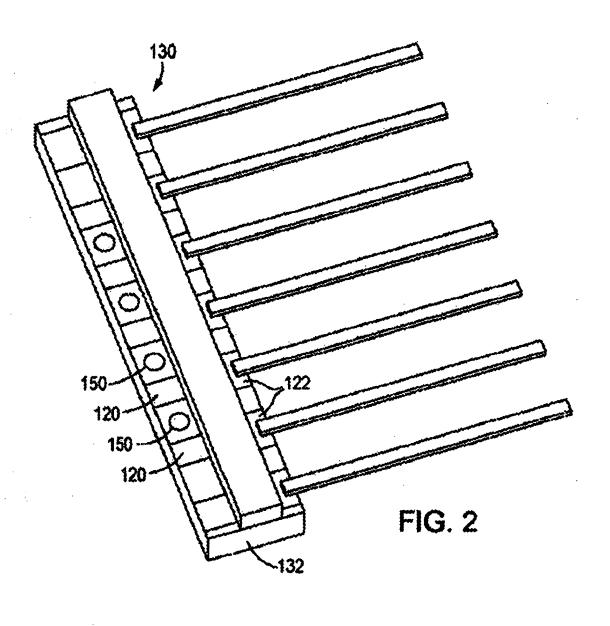
: July 25, 2006

INVENTOR(S)

: Robert L. Payer

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Delete Sheet 2 of 3 of the issued patent and replace with the following Sheet 2 of 3:



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APPLICATION NO. : 09/884844

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It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Delete Sheet 3 of 3 of the issued patent and replace with the following sheet 3 of 3:

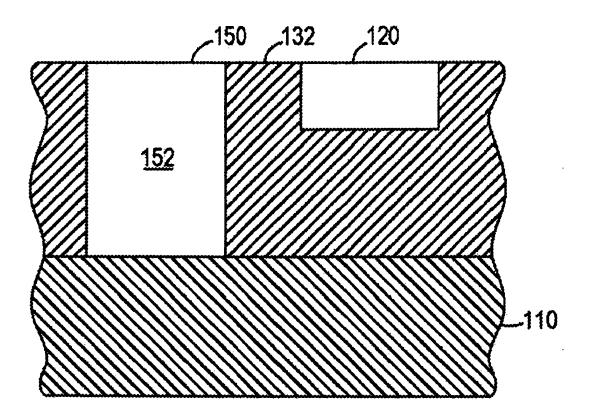


FIG. 3